SCDS057G - MARCH 1998 - REVISED OCTOBER 2003

- 5-Ω Switch Connection Between Two Ports
- Rail-to-Rail Switching on Data I/O Ports
- I_{off} Supports Partial-Power-Down Mode Operation

OE 1 5 VCC

description/ordering information

The SN74CBTLV1G125 features a single high-speed line switch. The switch is disabled when the output-enable (OE) input is high.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡	
400C to 050C	SOT (SOT-23) – DBV	Tape and reel	SN74CBTLV1G125DBVR	V25_	
-40°C to 85°C	SOT (SC-70) - DCK	Tape and reel	SN74CBTLV1G125DCKR	VM_	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUT OE	FUNCTION	
L	A port = B port	
Н	Disconnect	



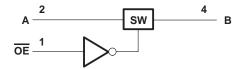
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



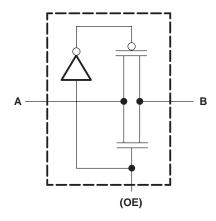
[‡] The actual top-side marking has one additional character that designates the assembly/test site.

SCDS057G - MARCH 1998 - REVISED OCTOBER 2003

logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	. $-0.5\ V$ to 4.6 V
Input voltage range, V _I (see Note 1)	. $-0.5\ V$ to 4.6 V
Continuous channel current	128 mA
Input clamp current, I _{IK} (V _{I/O} < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
Storage temperature range, T _{stq}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT	
VCC	V _{CC} Supply voltage			V	
VIH	High-level control input voltage $ \frac{V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}}{V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}} $.,	
				V	
.,	$V_{CC} = 2.3 \text{ V}$ to 2.7 V		0.7).7	
V_{IL}	Low-level control input voltage $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V	
TA	Operating free-air temperature	-40	85	°C	

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

The package thermal impedance is calculated in accordance with JESD 51-7.

SCDS057G - MARCH 1998 - REVISED OCTOBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
VIK		$V_{CC} = 3 V$,	$I_{I} = -18 \text{ mA}$				-1.2	V
Ц		V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND				±1	μΑ
l _{off}		$V_{CC} = 0$,	V_{I} or $V_{O} = 0$ to 3.6	V			10	μΑ
Icc		$V_{CC} = 3.6 \text{ V},$	$I_{O} = 0$,	$V_I = V_{CC}$ or GND			10	μΑ
ΔI _{CC} ‡	Control inputs	$V_{CC} = 3.6 \text{ V},$	One input at 3 V,	Other inputs at V _{CC} or GND			300	μΑ
Ci	Control inputs	$V_I = 3 V \text{ or } 0$				2.5		pF
C _{io(OFI}	=)	$V_{O} = 3 \text{ V or } 0,$	OE = V _{CC}			7		pF
			\	I _I = 64 mA		7	10	
		$V_{CC} = 2.3 \text{ V},$ TYP at $V_{CC} = 2.5 \text{ V}$	V _I = 0	I _I = 24 mA		7	10	
r _{on} §		111 at vCC = 2.0 v	V _I = 1.7 V,	I _I = 15 mA		15	25	Ω
iona		N 0	V 0	I _I = 64 mA		5	7	22
		V _{CC} = 3 V	V _I = 0	I _I = 24 mA		5	7	
			V _I = 2.4 V,	I _I = 15 mA		10	15	

[†] All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

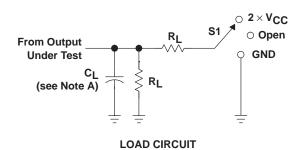
PARAMETER	FROM	TO	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	
$t_{pd}\P$	A or B	B or A		0.15		0.25	ns
t _{en}	ŌĒ	A or B	1	4	1	4	ns
^t dis	ŌĒ	A or B	1	5	1	4.1	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

[‡] This is the increase in supply current for each input that is at the specified voltage level, rather than VCC or GND.

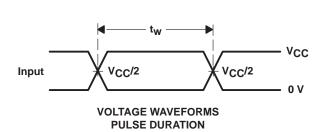
[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

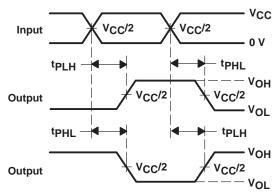
PARAMETER MEASUREMENT INFORMATION



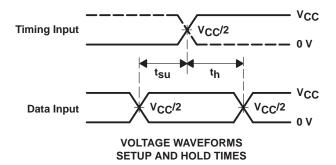
TEST	S1
tPLH/tPHL	Open
t _{PLZ} /t _{PZL}	2×V _{CC}
tPHZ/tPZH	GND

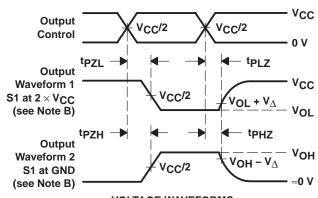
VCC	CL	RL	$v_{\scriptscriptstyle\Delta}$
2.5 V ±0.2 V	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	50 pF	500 Ω	0.3 V





VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES **INVERTING AND NONINVERTING OUTPUTS**





VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

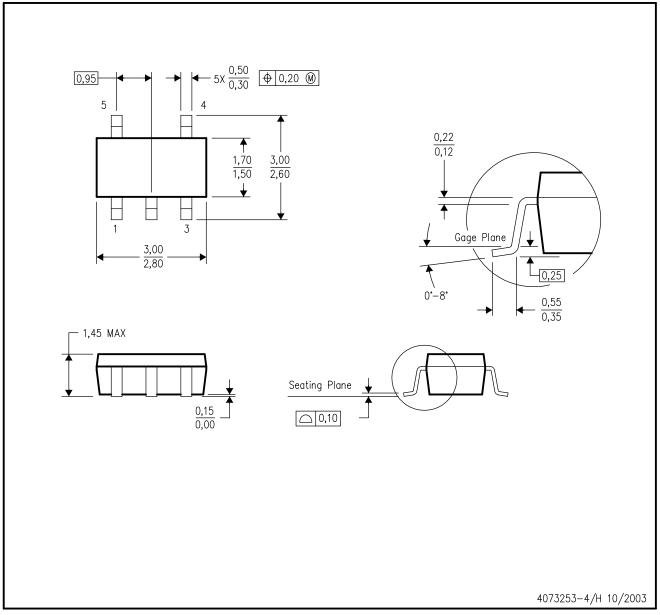
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpZL and tpZH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



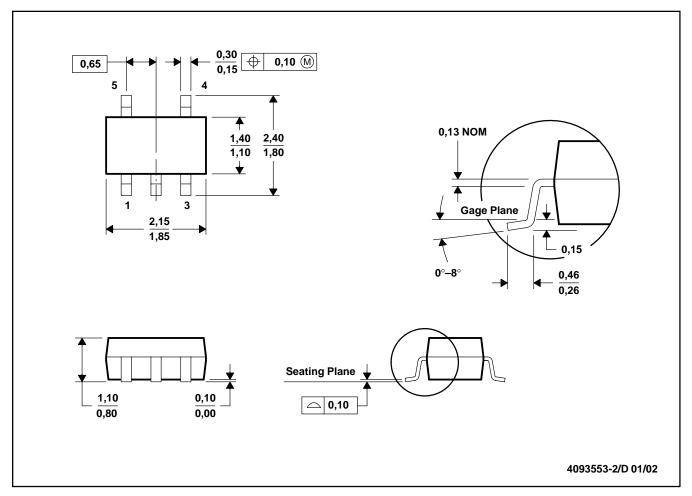
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- C. Body dimensions do not include mold fla D. Falls within JEDEC MO—178 Variation AA. Body dimensions do not include mold flash or protrusion.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-203

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2003, Texas Instruments Incorporated